

**WHAT IS CLAIMED IS:**

1. A cooler for cooling of electronic components comprising at least two heatsinks thermally connected with each other by heat spreading means, and at least one double inlet centrifugal blower comprising a casing with two inlets and an outlet, an impeller with an axle and an electric drive, said cooler is thermally connected with said electronic component, wherein

(i) each of said heatsinks comprises inflow and outflow openings, and thermally connected heat exchanging means and a base;

(ii) said double inlet centrifugal blower is located between said heatsinks thus each of said outflow openings is coincided with said closest inlet, so cooling air flows through said inflow openings, said heat exchanging means, said outflow openings and said inlets of said blower in a series way.

2. The cooler as in claim 1, wherein said base of at least one of said heatsinks is thermally connected with said electronic component.

3. The cooler as in claim 1, wherein said heat spreading means are made as at least one heat pipe comprising evaporator and condenser parts that thermally connected with said bases of two different heatsinks.

4. The cooler as in claim 1, wherein said heat spreading means are made as a high heat conductive plate located from one side of and perpendicularly to said bases.

5. The cooler as in claim 4, wherein said high heat conductive plate thermally connected with said electronic component.

6. The cooler as in claim 4, wherein said heatsinks and said high heat conductive plate made as a single whole.

7. The cooler as in claim 1, wherein said heat exchanging means are upstanding pins and/or fins contacting said base.